

TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

TLP626, TLP626-2, TLP626-4

Programmable Controllers
AC / DC-Input Module
Telecommunication

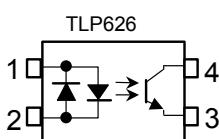
The TOSHIBA TLP626, -2 and -4 consist of gallium arsenide infrared emitting diodes connected in inverse parallel, optically coupled to a photo-transistor.

The TLP626-2 offers two isolated channels in an eight lead plastic DIP, while the TLP626-4 provides four isolated channels in a sixteen lead plastic DIP.

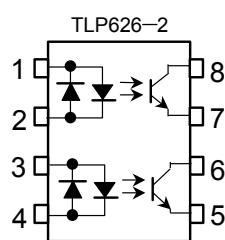
- Collector-emitter voltage: 55V(min.)
- Current transfer ratio

Classi- fication	Current Transfer Ratio(min.)			Marking Of Classi- fication
	Ta = 25°C		Ta = -25~75°C	
	I _F = ±1mA V _{CE} = 0.5V	I _F = ±0.5mA V _{CE} = 1.5V	I _F = ±1mA V _{CE} = 0.5V	
Rank BV	200%	100%	100%	BV
Standard	100%	50%	50%	BV, blank

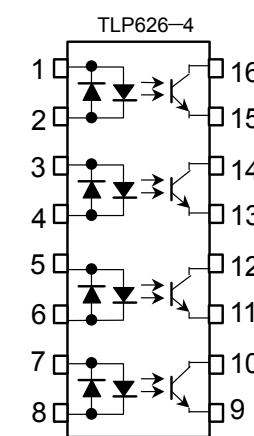
- Isolation voltage: 5000V_{rms} min.
- UL recognized: UL1577, file no.E67349
- BSI approved: BS EN60065: 1994 certificate no.7426
BS EN60950: 1992 certificate no.7427
- Note: Application type name for certification test,
please use standard product type name, i.e.
TLP626(BV): TLP626

Pin Configuration (top view)

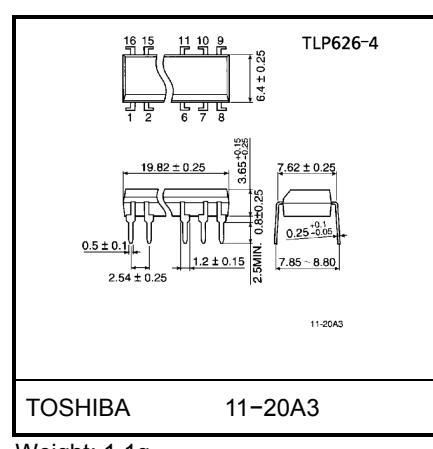
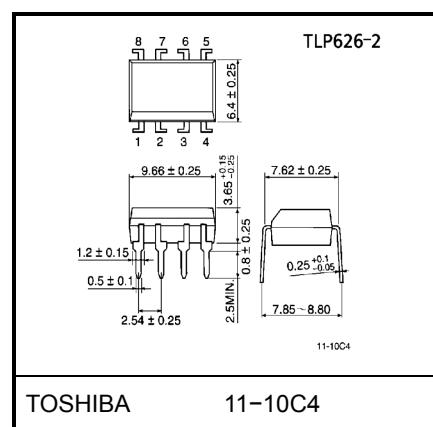
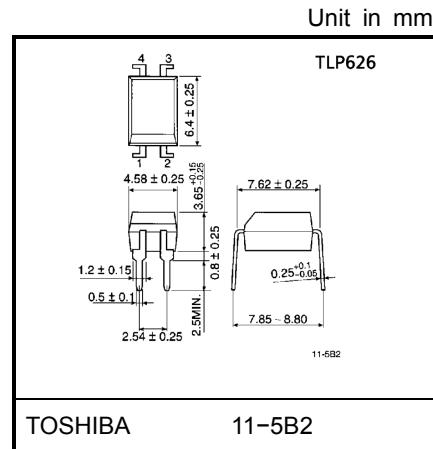
1 : Anode
Cathode
2 : Cathode
Anode
3 : Emitter
4 : Collector



1, 3 : Anode
Cathode
2, 4 : Cathode
Anode
5, 7 : Emitter
6, 8 : Collector



1, 3, 5, 7 : Anode, Cathode
2, 4, 6, 8 : Cathode, Anode
9, 11, 13, 15 : Emitter
10, 12, 14, 16 : Collector



Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating		Unit
		TLP626	TLP626-2 TLP626-4	
LED	Forward current	I _F	60	mA
	Forward current derating	ΔI _F / °C	-0.7(Ta ≥ 39°C)	mA / °C
	Pulse forward current	I _{FP}	1(100μs pulse,100pps)	A
	Power dissipation (1 circuit)	P _D	100	mW
	Power dissipation derating (Ta ≥ 25°C, 1 circuit)	ΔP _D / °C	-1.0	mW / °C
	Junction temperature	T _j	125	°C
Detector	Collector-emitter voltage	V _{CEO}	55	V
	Emitter-collector voltage	V _{ECO}	7	V
	Collector current	I _C	50	mA
	Collector power dissipation (1 circuit)	P _C	150	mW
	Collector power dissipation derating (Ta ≥ 25°C, 1 circuit)	ΔP _C / °C	-1.5	mW / °C
	Junction temperature	T _j	125	°C
Storage temperature range		T _{stg}	-55~125	°C
Operating temperature range		P _{opr}	-55~100	°C
Lead soldering temperature		T _{sol}	260(10s)	°C
Total package power dissipation (1 circuit)		P _T	250	mW
Total package power dissipation derating (Ta ≥ 25°C, 1 circuit)		ΔP _T / °C	-2.5	mW / °C
Isolation voltage (Note 1)		BV _S	5000(AC, 1min., RH≤60%)	V _{rms}

(Note 1) Device considered a two terminal: LED side pins shorted together, and detector side pins shorted together.

Recommended Operating Conditions

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	V _{CC}	—	5	24	V
Forward current	I _{F(RMS)}	—	1.6	20	mA
Collector current	I _C	—	1	10	mA
Operating temperature	T _{opr}	-25	—	75	°C

Individual Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Typ.	Max.	Unit
LED	Forward voltage	V _F	I _F = ±10mA	1.0	1.15	1.3	V
	Reverse current	I _F	V _F = ±0.7V	—	2.5	20	µA
	Capacitance	C _T	V = 0, f = 1MHz	—	60	—	pF
Detector	Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C = 0.5mA	55	—	—	V
	Emitter-collector breakdown voltage	V _{(BR)ECO}	I _E = 0.1mA	7	—	—	V
	Collector dark current	I _{CEO}	V _{CE} = 24V	—	10	10	nA
			V _{CE} = 24V, Ta = 85°C	—	2	50	µA
	Capacitance collector to emitter	C _{CE}	V=0, f=1MHz	—	12	—	pF

Coupled Electrical Characteristics (Ta = 25°C)

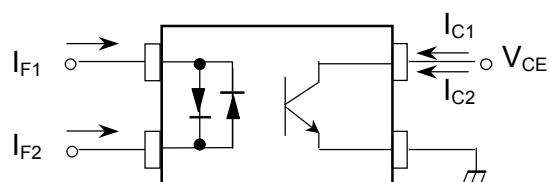
Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Current transfer ratio	I _C / I _F	I _F = ±1mA, V _{CE} = 0.5V rank BV	100	—	1200	%
			200	—	1200	
Low input CTR	I _C / I _{F(low)}	I _F = ±0.5mA, V _{CE} = 1.5V rank BV	50	—	—	%
			100	—	—	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C = 0.5mA, I _F = ±1mA	—	—	0.4	V
		I _C = 1mA, I _F = ±1mA rank BV	—	0.2	—	
		—	—	0.4	—	
Off-state collector current	I _{C(off)}	V _F = ±0.7V, V _{CE} = 24V	—	1	10	µA
CTR symmetry *1	I _{C(ratio)}	I _C (I _F = -1mA) / I _C (I _F = 1mA)	0.5	—	2	—

Coupled Electrical Characteristics (Ta = -25~75°C)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Current transfer ratio	I _C / I _F	I _F = 1mA, V _{CE} = 0.5V rank BV	50	—	—	%
			100	—	—	
Low input CTR	I _C / I _{F(low)}	I _F = 0.5mA, V _{CE} = 1.5V rank BV	—	50	—	%
			—	100	—	

*1

$$I_{C(ratio)} = \frac{I_{C2}(I_F = I_{F2}, V_{CE} = 5V)}{I_{C1}(I_F = I_{F1}, V_{CE} = 5V)}$$



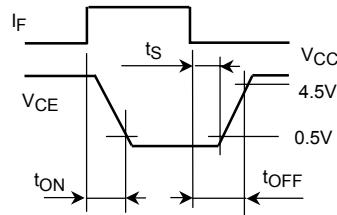
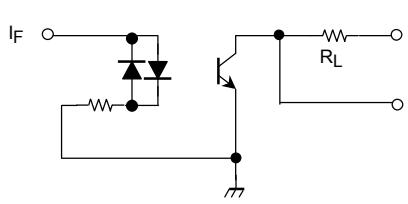
Isolation Characteristics (Ta = 25°C)

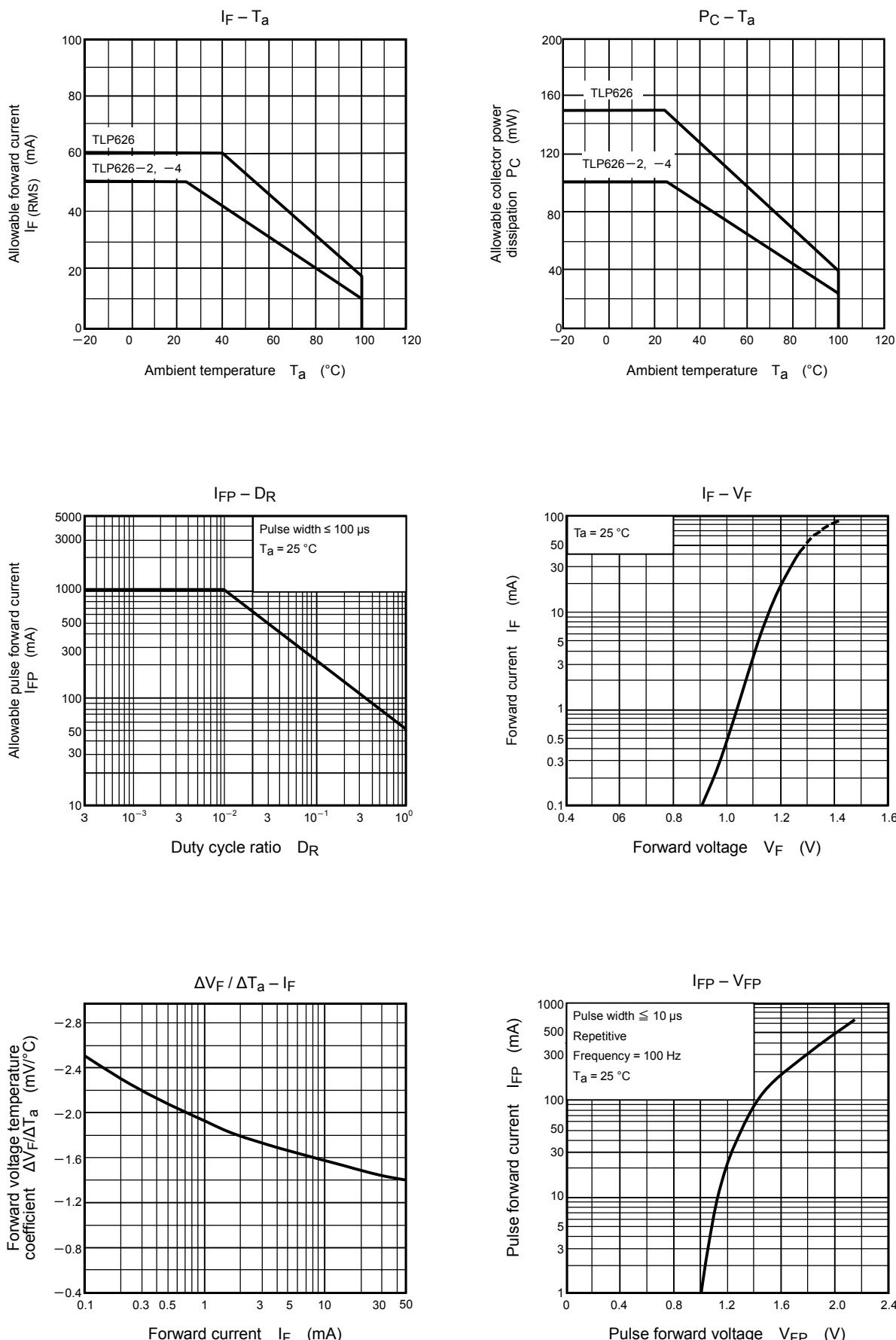
Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Capacitance input to output	C _S	V _S = 0, f = 1MHz	—	0.8	—	pF
Isolation resistance	R _S	V _S = 500V	5×10 ¹⁰	10 ¹⁴	—	Ω
Isolation voltage	BV _S	AC, 1 minute	5000	—	—	Vrms
		AC, 1 second, in oil	—	10000	—	
		DC, 1 minute, in oil	—	10000	—	Vdc

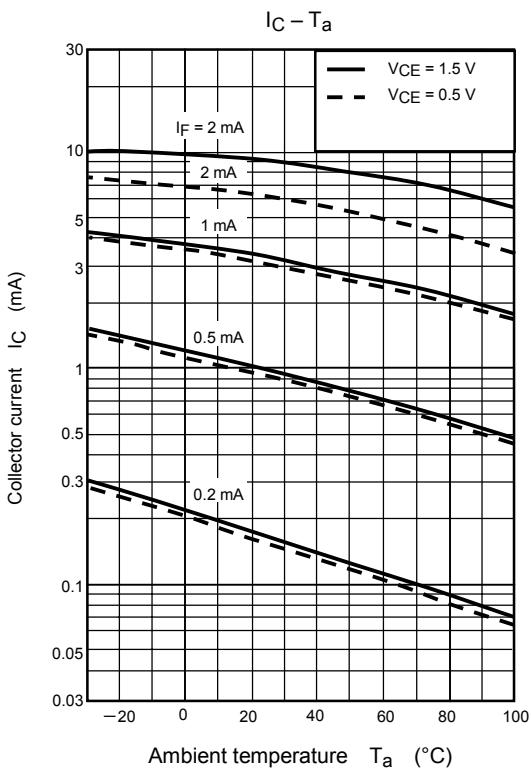
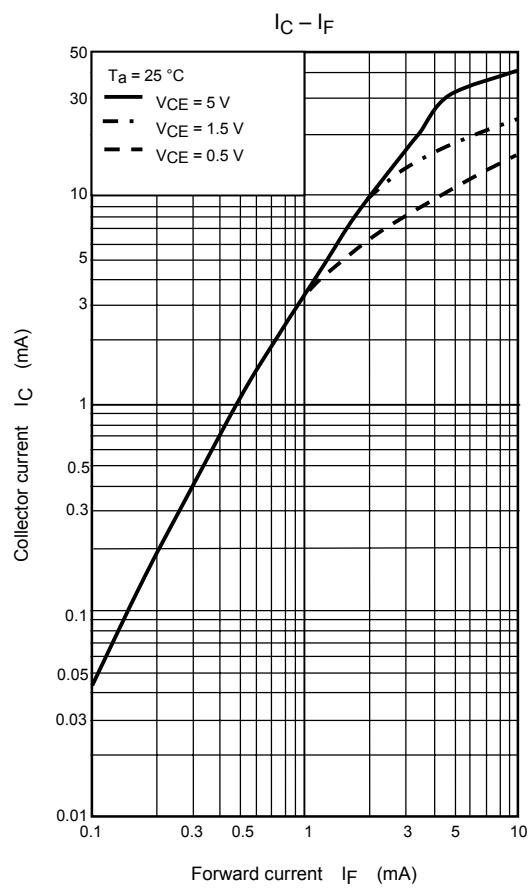
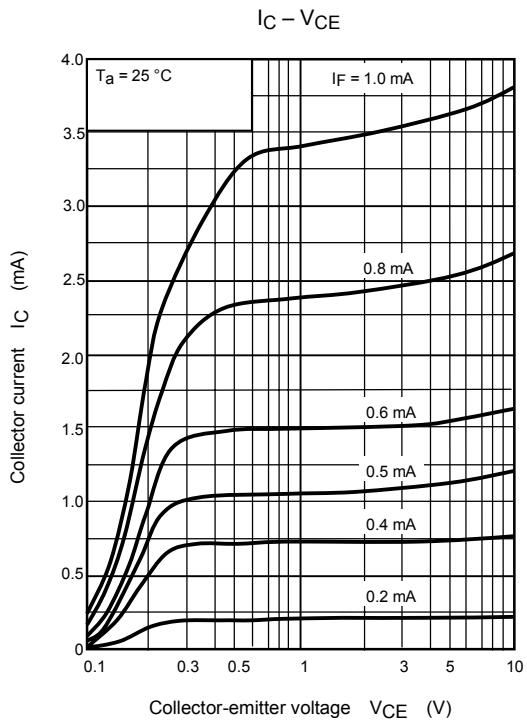
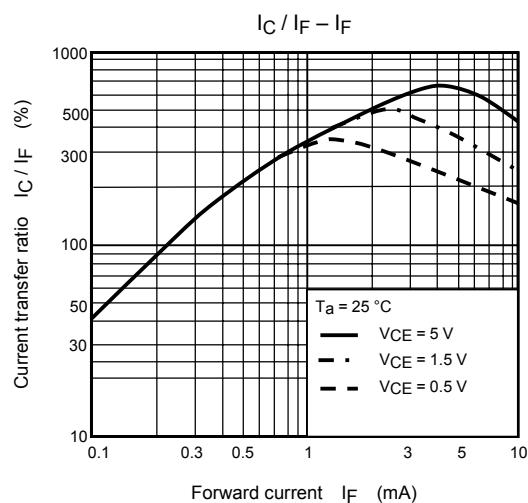
Switching Characteristics (Ta = 25°C)

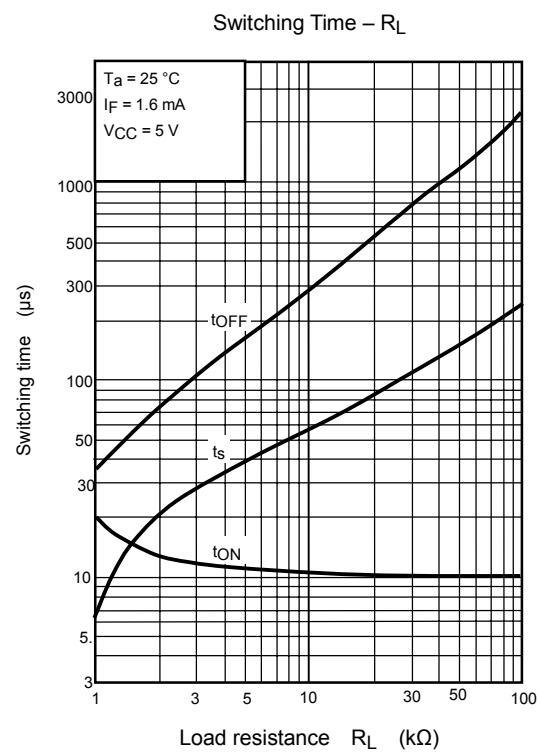
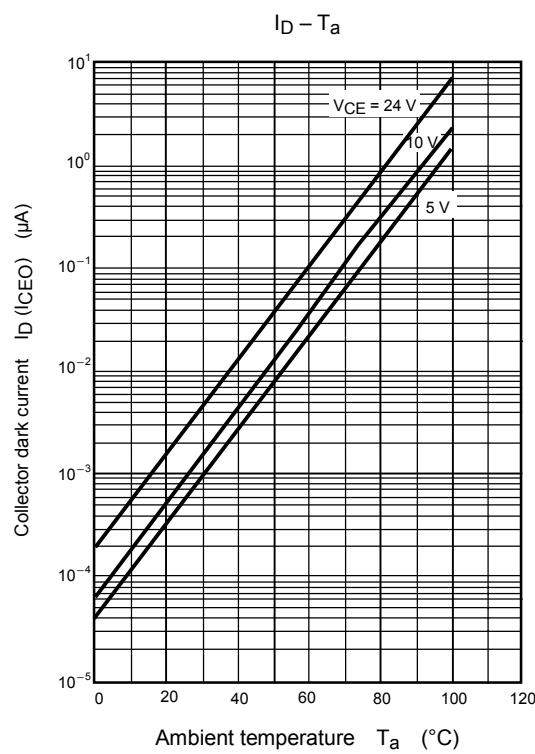
Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Rise time	t _r	V _{CC} = 10V, I _C = 2mA R _L = 100Ω	—	8	—	μs
Fall time	t _f		—	8	—	
Turn-on time	t _{on}		—	10	—	
Turn-off time	t _{off}		—	8	—	
Turn-on time	t _{ON}	R _L = 4.7kΩ (Fig.1) V _{CC} = 5 V, I _F = ±1.6mA	—	10	—	μs
Storage time	t _s		—	50	—	
Turn-off time	T _{OFF}		—	300	—	

Fig. 1 Switching operating conditions









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